

STD15N65M5-VB Datasheet N-Channel 650V (D-S) Super Junction Power MOSFET

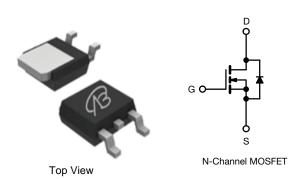
| PRODUCT SUMMARY | | | | | |
|--|------------------------|-------|--|--|--|
| V _{DS} (V) at T _J max. | 650 | | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V | 0.340 | | | |

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)



TO-252



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | | |
|--|--|-------------------------|-----------------------------------|-------------|-------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | | V _{DS} | 650 | V | |
| Gate-source voltage | | | V_{GS} | ± 30 | V | |
| Continuous drain surrent (T = 150 °C) | V _{GS} at 10 V | T _C = 25 °C | - I _D | 12 | | |
| Continuous drain current (T _J = 150 °C) | | T _C = 100 °C | | 7 | Α | |
| Pulsed drain current ^a | | | I _{DM} | 36 | | |
| Linear derating factor | | | | 1.7 | W/°C | |
| Single pulse avalanche energy b | | E _{AS} | 320 | mJ | | |
| Maximum power dissipation | | | P_{D} | 180 | W | |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C | |
| Drain-source voltage slope | T _J = 125 °C | | dV/dt | 50 | V/ns | |
| Reverse diode dV/dt ^d | | | αν/αι | 5.1 | V/IIS | |
| Soldering recommendations (peak temperature) ^c | Idering recommendations (peak temperature) ^c For 10 s | | | 260 | °C | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 Ω , I_{AS} = 6 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------------|-------------------|------|------|--------------|--|--|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT | | |
| Maximum junction-to-ambient | R _{thJA} | = | 62 | °C/W | | |
| Maximum junction-to-case (drain) | R _{thJC} | - | 0.85 | G/ VV | | |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|--|------|-------|-------|------|
| Static | | • | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | | 650 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Reference | e to 25 °C, I _D = 1 mA | - | 1.08 | - | V/°C |
| Gate-source threshold Voltage (N) | V _{GS(th)} | V _{DS} = | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ | | - | 4.0 | V |
| | | $V_{GS} = \pm 20 \text{ V}$ | | - | - | ± 100 | nA |
| Gate-source leakage | I _{GSS} | | V _{GS} = ± 30 V | - | - | ± 1 | μA |
| | | V _{DS} = 650 V, V _{GS} = 0 V | | - | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 520 \ | /, V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D =4A | - | 0.340 | - | Ω |
| Forward transconductance | 9 _{fs} | V_{DS} | = 30 V, I _D = 12 A | - | 8.7 | - | S |
| Dynamic | | | - | I | I | l | l. |
| Input capacitance | C _{iss} | | $V_{GS} = 0 V$, | _ | 2500 | _ | |
| Output capacitance | C _{oss} | | $V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ | | 51 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1 MHz | | _ | 12 | - | pF |
| Effective output capacitance, energy related ^a | C _{o(er)} | V _{DS} = 0 V to 480 V, V _{GS} = 0 V | | - | 48 | - | |
| Effective output capacitance, time related ^b | $C_{o(tr)}$ | | | - | 205 | - | |
| Total gate charge | Qg | V _{GS} = 10 V | | - | 25 | - | nC |
| Gate-source charge | Q_{gs} | | | - | 8 | - | |
| Gate-drain charge | Q _{qd} | 1 | | | 10 | - | |
| Turn-on delay time | t _{d(on)} | $V_{DD} = 480 \text{ V}, I_{D} = 12 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$ f = 1 MHz, open drain | | - | 12 | 24 | - ns |
| Rise time | t _r | | | - | 14 | 23 | |
| Turn-off delay time | t _{d(off)} | | | - | 61 | 110 | |
| Fall time | t _f | | | - | 16 | - | |
| Gate input resistance | Rq | | | 0.3 | 0.7 | 1.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | • | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 12 | _ |
| Pulsed diode forward current | I _{SM} | | | - | - | 36 | Α |
| Diode forward voltage | V_{SD} | T _J = 25 °C, I _S = 12 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | $T_J = 25 \text{ °C}, I_F = I_S = 12 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$ | | - | 416 | 832 | ns |
| Reverse recovery charge | Q _{rr} | | | - | 6.4 | 12.8 | μC |
| Reverse recovery current | I _{RRM} | | | _ | 27 | _ | Α |

Notes

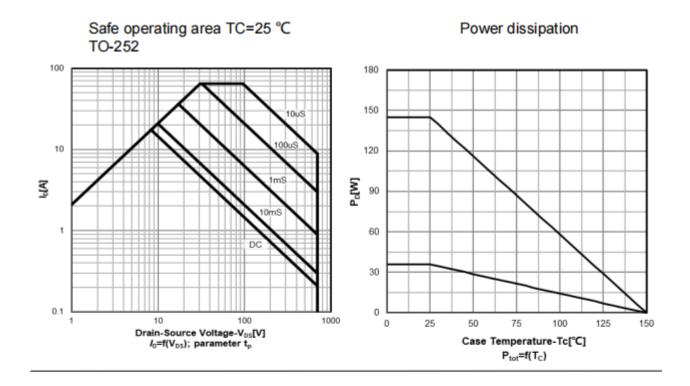
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- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

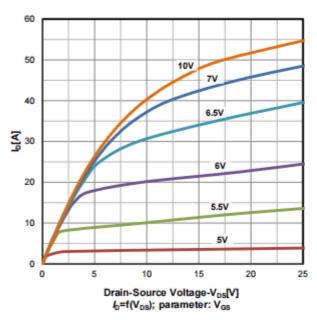
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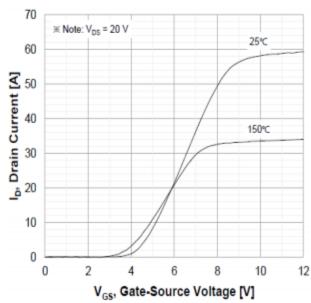
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Typ. output characteristics T_i =25 $^{\circ}C$



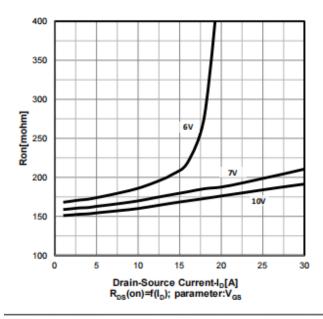
Transfer characteristics



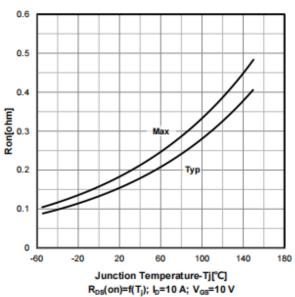
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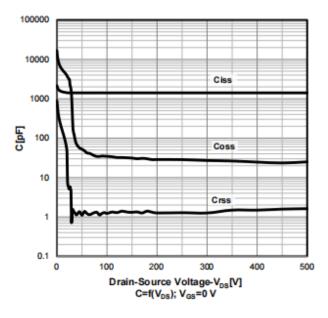
Typ. drain-source on-state resistance



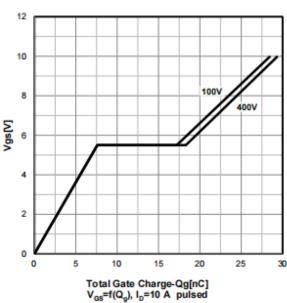
On-resistance vs temperature



Typ. capacitances



Typ. gate charge characteristics

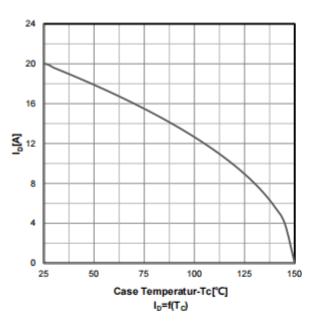


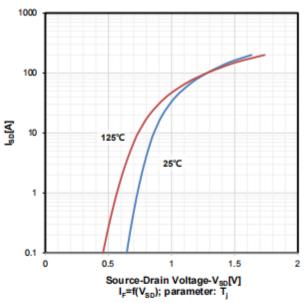
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Drain current vs temperature

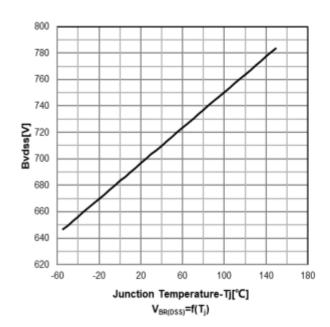
Forward characteristics of reverse diode

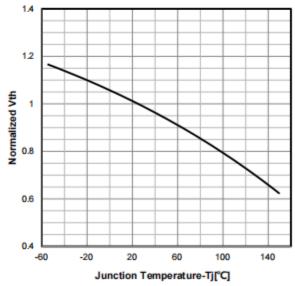




Drain-source breakdown voltage

Normalized V_{GS(th)} characteristics

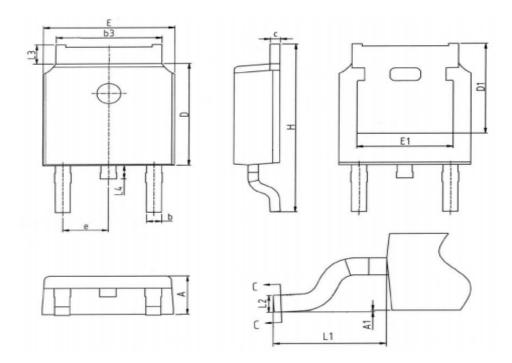




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Package Outline: TO 252



COMMON DIMENSIONS

| SYMBOL | UNIT(mm) | | | | | |
|--------|----------|-------|-------|--|--|--|
| SIMBOL | MIN | NOM | MAX | | | |
| A | 2.20 | 2.30 | 2.40 | | | |
| A1 | 0.00 | - | 0.127 | | | |
| b | 0.66 | 0.78 | 0.90 | | | |
| b3 | 5.16 | 5.31 | 5.46 | | | |
| c | 0.43 | 0.53 | 0.63 | | | |
| D | 5.98 | 6.10 | 6.22 | | | |
| D1 | 5.30REF | | | | | |
| E | 6.40 | 6.75 | | | | |
| E1 | 4.63 | - | - | | | |
| e | 2.286BSC | | | | | |
| H | 9.40 | 10.10 | 10.50 | | | |
| L1 | 2.90REF | | | | | |
| L2 | 0.51BSC | | | | | |
| L3 | 0.88 | 1.08 | 1.28 | | | |
| L4 | 0.50 | 0.80 | 1.00 | | | |

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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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